

Information note

N° 023/22

Dear customer,

With this Infineon Technologies AG information note, we would like to inform you about the following

Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to Phoenix Silicon International Corporation, Hsin Chu, Taiwan



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Information note

N° 023/22

► **Products affected**

Please refer to attached affected product list
 “INF_023-22_[customer-no].pdf”

► **Detailed change information**

Subject Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to Phoenix Silicon International Corporation, Hsin Chu, Taiwan for certain FET wafers. Wafer front side processing site and wafer probe site after backside processing are not changed.

Reason The wafer backside processing of the affected products will be transferred to Phoenix Silicon International Corporation, Hsin Chu, Taiwan according to the global Infineon production strategy.

Description	Old		New	
Wafer backgrind and backmetal	■	Xintec Inc., Taoyuan City, Taiwan	■	Phoenix Silicon International Corporation, Hsin Chu, Taiwan

► **Product identification**

Traceability assured via internal part tracking.

► **Impact of change**

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

► **Attachments**

2_cip02322 Qualification report

► **Intended start of delivery**

2022-07-01

If you have any questions, please do not hesitate to contact your local sales office.

RESTRICTED

Qualification Test Report



Information note N°: 023/22

Date: 2022-03-01

Title: Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to Phoenix Silicon International, Hsin Chu, Taiwan

Reason for choosing the following test vehicles:

relevant BE and die size; process released on same technology in similar products

Scope of qualification:

Change of wafer backside processing from Xintec to PSI

Assessment of Q-Results:

Pass

Stress test	Abbreviation	Test conditions	Readout	IRSM836-015MA	IRSM505-015PA
				fails / stressed	fails / stressed
Temperature Cycling JESD22-A104	TC	with preconditioning	1000 x	0 / 77	0 / 77
Unbiased Temperature/Humidity JESD22-A118	UHAST	with preconditioning Ta = 130 °C, RH = 85%	96 h	0 / 77	0 / 77

INF 023/22

Change of wafer backside processing from Xintec Inc., Taoyuan City, Taiwan to
Phoenix Silicon International Corporation, Hsin Chu, Taiwan



Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
IRSM836-024MA	SP001541026	IRSM836-024MA	QFN 12X12 36L	IRSM836-024MA
IRSM836-035MA	SP001539604	IRSM836-035MA	QFN 12X12 36L	IRSM836-035MA
IRSM836-035MB	SP001544304	IRSM836-035MB	QFN 12X12 27L	IRSM836-035MB
IRSM836-044MA	SP001543350	IRSM836-044MA	QFN 12X12 36L	IRSM836-044MA
IRSM836-045MA	SP001547052	IRSM836-045MA	QFN 12X12 37L	IRSM836-045MA